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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 6721
Morio GAKU et al. : Docket No. 2000-1033A
Serial No. 09/625,493 : Group Art Unit 1771
Filed July 25, 2000 : Examiner J. Pierce

GLASS FABRIC BASE MATERIAL/
THERMOSETTING RESIN COPPER-CLAD
LAMINATE HAVING A HIGH-ELASTICITY :

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

RESPONSE

Assistant Commissioner for Patents,
Washington, D.C.

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TC 1700

Sir:

In response to the Official Action dated February 27, 2002, the period for response having been extended for one month by the attached petition, please amend the present application as follows:

IN THE CLAIMS:

Please amend claims 1 to 5 as follows:

1. (Amended) A copper-clad laminate of a glass fabric/thermosetting resin base material formed of prepreg obtained by impregnating a glass fabric base material made of a glass woven fabric having a thickness of 25 to 150 μm , a weight of 15 to 165 g/m^2 and a gas permeability of 1 to 20 $\text{cm}^3/\text{cm}^2/\text{sec}$. with a thermosetting resin composition and drying it.

2. (Amended) The copper-clad laminate according to claim 1, wherein the thermosetting resin composition in the copper-clad laminate contains an insulating inorganic filler in an amount of 10 to 80 % by weight based on the above resin composition.